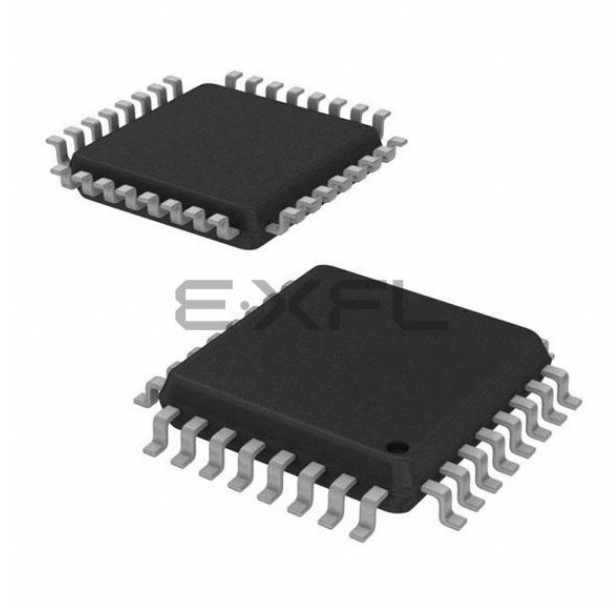

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"Embedded - Microcontrollers" refer to small, integrated circuits designed to perform specific tasks within larger systems. These microcontrollers are essentially compact computers on a single chip, containing a processor core, memory, and programmable input/output peripherals. They are called "embedded" because they are embedded within electronic devices to control various functions, rather than serving as standalone computers. Microcontrollers are crucial in modern electronics, providing the intelligence and control needed for a wide range of applications.

Applications of "Embedded - Microcontrollers"

Details	
Product Status	Active
Core Processor	8051
Core Size	8-Bit
Speed	50MHz
Connectivity	SMBus (2-Wire/I²C), CANbus, LINbus, SPI, UART/USART
Peripherals	POR, PWM, Temp Sensor, WDT
Number of I/O	25
Program Memory Size	64KB (64K x 8)
Program Memory Type	FLASH
EEPROM Size	-
RAM Size	4.25K x 8
Voltage - Supply (Vcc/Vdd)	1.8V ~ 5.25V
Data Converters	A/D 25x12b
Oscillator Type	Internal
Operating Temperature	-40°C ~ 125°C (TA)
Mounting Type	Surface Mount
Package / Case	32-LQFP
Supplier Device Package	32-LQFP (7x7)
Purchase URL	https://www.e-xfl.com/product-detail/silicon-labs/c8051f502-iqr

Table 3.1. Pin Definitions for the C8051F50x/F51x(Continued)

Name	Pin ‘F500/1/4/5 (48-pin)	Pin F508/9-F510/1 (40-pin)	Pin ‘F502/3/6/7 (32-pin)	Type	Description
P3.7	19	11	—	D I/O	Port 3.7.
P4.0	18	—	—	D I/O	Port 4.0. See SFR Definition 20.28 for a description.
P4.1	17	—	—	D I/O	Port 4.1.
P4.2	16	—	—	D I/O	Port 4.2.
P4.3	15	—	—	D I/O	Port 4.3.
P4.4	14	—	—	D I/O	Port 4.4.
P4.5	13	—	—	D I/O	Port 4.5.
P4.6	10	—	—	D I/O	Port 4.6.
P4.7	9	—	—	D I/O	Port 4.7.

5. Electrical Characteristics

5.1. Absolute Maximum Specifications

Table 5.1. Absolute Maximum Ratings

Parameter	Conditions	Min	Typ	Max	Units
Ambient Temperature under Bias		–55	—	135	°C
Storage Temperature		–65	—	150	°C
Voltage on V_{REGIN} with Respect to GND		–0.3	—	5.5	V
Voltage on V_{DD} with Respect to GND		–0.3	—	2.8	V
Voltage on VDDA with Respect to GND		–0.3	—	2.8	V
Voltage on V_{IO} with Respect to GND		–0.3	—	5.5	V
Voltage on any Port I/O Pin or $\overline{RST}$ with Respect to GND		–0.3	—	V_{IO} + 0.3	V
Maximum Total Current through V_{REGIN} or GND		—	—	500	mA
Maximum Output Current Sunk by $\overline{RST}$ or any Port Pin		—	—	100	mA
Maximum Output Current Sourced by any Port Pin		—	—	100	mA

Note: Stresses outside of the range of the "Absolute Maximum Ratings" may cause permanent damage to the device. This is a stress rating only and functional operation of the devices at those or any other conditions above those indicated in the operation listings of this specification is not implied. Exposure to maximum rating conditions for extended periods may affect device reliability.

5.2. Electrical Characteristics

Table 5.2. Global Electrical Characteristics

–40 to +125 °C, 24 MHz system clock unless otherwise specified.

Parameter	Conditions	Min	Typ	Max	Units
Supply Input Voltage (V_{REGIN})		1.8	—	5.25	V
Digital Supply Voltage (V_{DD})	System Clock ≤ 25 MHz	V_{RST}[1]	—	2.75	V
	System Clock > 25 MHz	2		2.75	
Analog Supply Voltage (VDDA)	System Clock ≤ 25 MHz	V_{RST}[1]	—	2.75	V
(Must be connected to V_{DD})	System Clock > 25 MHz	2		2.75	
Digital Supply RAM Data Retention Voltage			1.5		
Port I/O Supply Voltage (V_{IO})	Normal Operation	1.8[2]	—	5.25	V
SYSCLK (System Clock)[3]		0	—	50	MHz
T_{SYSH} (SYSCLK High Time)		9	—	—	ns
T_{SYSL} (SYSCLK Low Time)		9	—	—	ns
Specified Operating Temperature Range		–40	—	+125	°C
Digital Supply Current—CPU Active (Normal Mode, fetching instructions from Flash)					
I_{DD}[4]	V_{DD} = 2.1 V, F = 200 kHz	—	95	—	µA
	V_{DD} = 2.1 V, F = 1.5 MHz	—	700	—	µA
	V_{DD} = 2.1 V, F = 25 MHz	—	10	11	mA
	V_{DD} = 2.1 V, F = 50 MHz	—	19	21	mA

Notes:

1. Given in Table 5.4 on page 46.
2. V_{IO} should not be lower than the V_{DD} voltage.
3. SYSCLK must be at least 32 kHz to enable debugging.
4. Based on device characterization data; Not production tested. Does not include oscillator supply current.
5. IDD can be estimated for frequencies ≤ 12.5 MHz by simply multiplying the frequency of interest by the frequency sensitivity number for that range. When using these numbers to estimate I_{DD} for >12.5 MHz, the estimate should be the current at 50 MHz minus the difference in current indicated by the frequency sensitivity number. For example: V_{DD} = 2.6 V; F = 20 MHz, I_{DD} = 26 mA - (50 MHz - 20 MHz) * 0.48 mA/MHz = 11.6 mA.
6. Idle IDD can be estimated for frequencies ≤ 1 MHz by simply multiplying the frequency of interest by the frequency sensitivity number for that range. When using these numbers to estimate Idle I_{DD} for >1 MHz, the estimate should be the current at 50 MHz minus the difference in current indicated by the frequency sensitivity number.
   For example: V_{DD} = 2.6 V; F = 5 MHz, Idle I_{DD} = 21 mA – (50 MHz – 5 MHz) x 0.41 mA/MHz = 2.6 mA.

Table 5.10. Temperature Sensor Electrical Characteristics

VDDA = 1.8 to 2.75 V, –40 to +125 °C unless otherwise specified.

Parameter	Conditions	Min	Typ	Max	Units
Linearity		—	±0.1	—	°C
Slope		—	3.33	—	mV/°C
Slope Error*		—	±100	—	µV/°C
Offset	Temp = 0 °C	—	856	—	mV
Offset Error*	Temp = 0 °C	—	±14	—	mV
Power Supply Current		—	21	—	µA
Tracking Time		12	—	—	µs
***Note:** Represents one standard deviation from the mean.					

Table 5.11. Voltage Reference Electrical Characteristics

VDDA = 1.8 to 2.75 V, –40 to +125 °C unless otherwise specified.

Parameter	Conditions	Min	Typ	Max	Units
Internal Reference (REFBE = 1)					
Output Voltage	25 °C ambient (REFLV = 0)	1.45	1.50	1.55	V
	25 °C ambient (REFLV = 1), V_{DD} = 2.6 V	2.15	2.20	2.25	
VREF Short-Circuit Current		—	5	10	mA
VREF Temperature Coefficient		—	33	—	ppm/°C
Power Consumption	Internal	—	30	50	µA
Load Regulation	Load = 0 to 200 µA to AGND	—	3	—	µV/µA
VREF Turn-on Time 1	4.7 µF and 0.1 µF bypass	—	1.5	—	ms
VREF Turn-on Time 2	0.1 µF bypass	—	46	—	µs
Power Supply Rejection		—	1.3	—	mV/V
External Reference (REFBE = 0)					
Input Voltage Range		1.5	—	V_{DDA}	V
Input Current	Sample Rate = 200 ksps; VREF = 1.5 V	—	2.2	—	µA
Power Specifications					
Reference Bias Generator	REFBE = 1 or TEMPE = 1	—	21	40	µA

SFR Definition 6.11. ADC0LTH: ADC0 Less-Than Data High Byte

Bit	7	6	5	4	3	2	1	0
Name	ADC0LTH[7:0]							
Type	R/W							
Reset	0	0	0	0	0	0	0	0

SFR Address = 0xC6; SFR Page = 0x00

Bit	Name	Function
7:0	ADC0LTH[7:0]	**ADC0 Less-Than Data Word High-Order Bits.**

SFR Definition 6.12. ADC0LTL: ADC0 Less-Than Data Low Byte

Bit	7	6	5	4	3	2	1	0
Name	ADC0LTL[7:0]							
Type	R/W							
Reset	0	0	0	0	0	0	0	0

SFR Address = 0xC5; SFR Page = 0x00

Bit	Name	Function
7:0	ADC0LTL[7:0]	**ADC0 Less-Than Data Word Low-Order Bits.**

6.4.1. Window Detector In Single-Ended Mode

Figure 6.6 shows two example window comparisons for right-justified data with ADC0LTH:ADC0LTL = 0x0200 (512d) and ADC0GTH:ADC0GTL = 0x0100 (256d). The input voltage can range from 0 to V_{REF} x (4095/4096) with respect to GND, and is represented by a 12-bit unsigned integer value. The repeat count is set to one. In the left example, an AD0WINT interrupt will be generated if the ADC0 conversion word (ADC0H:ADC0L) is within the range defined by ADC0GTH:ADC0GTL and ADC0LTH:ADC0LTL (if 0x0100 < ADC0H:ADC0L < 0x0200). In the right example, and AD0WINT interrupt will be generated if the ADC0 conversion word is outside of the range defined by the ADC0GT and ADC0LT registers (if ADC0H:ADC0L < 0x0100 or ADC0H:ADC0L > 0x0200). Figure 6.7 shows an example using left-justified data with the same comparison values.

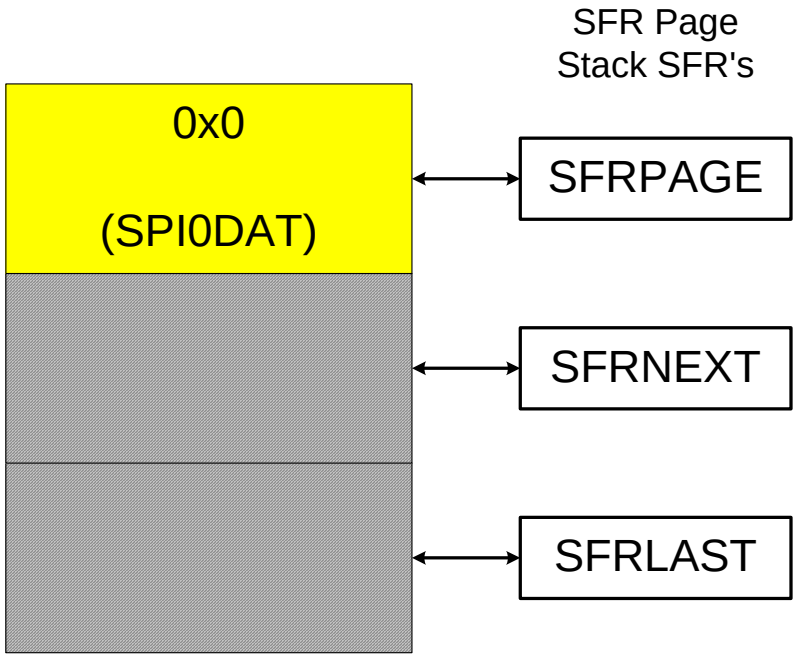

Figure 13.2. SFR Page Stack While Using SFR Page 0x0 To Access SPI0DAT

While CIP-51 executes in-line code (writing values to SPI0DAT in this example), the CAN0 Interrupt occurs. The CIP-51 vectors to the CAN0 ISR and pushes the current SFR Page value (SFR Page 0x00) into SFRNEXT in the SFR Page Stack. The SFR page needed to access CAN's SFRs is then automatically placed in the SFRPAGE register (SFR Page 0x0C). SFRPAGE is considered the "top" of the SFR Page Stack. Software can now access the CAN0 SFRs. Software may switch to any SFR Page by writing a new value to the SFRPAGE register at any time during the CAN0 ISR to access SFRs that are not on SFR Page 0x0C. See Figure 13.3.

SFR Definition 16.1. PCON: Power Control

Bit	7	6	5	4	3	2	1	0
Name	GF[5:0]						STOP	IDLE
Type	R/W						R/W	R/W
Reset	0	0	0	0	0	0	0	0

SFR Address = 0x87; SFR Page = All Pages

Bit	Name	Function
7:2	GF[5:0]	**General Purpose Flags 5–0.** These are general purpose flags for use under software control.
1	STOP	**Stop Mode Select.** Setting this bit will place the CIP-51 in Stop mode. This bit will always be read as 0. 1: CPU goes into Stop mode (internal oscillator stopped).
0	IDLE	**IDLE: Idle Mode Select.** Setting this bit will place the CIP-51 in Idle mode. This bit will always be read as 0. 1: CPU goes into Idle mode. (Shuts off clock to CPU, but clock to Timers, Interrupts, Serial Ports, and Analog Peripherals are still active.)

18.2. Configuring the External Memory Interface

Configuring the External Memory Interface consists of five steps:

1. Configure the Output Modes of the associated port pins as either push-pull or open-drain (push-pull is most common), and skip the associated pins in the crossbar.
2. Configure Port latches to “park” the EMIF pins in a dormant state (usually by setting them to logic 1).
3. Select Multiplexed mode or Non-multiplexed mode.
4. Select the memory mode (on-chip only, split mode without bank select, split mode with bank select, or off-chip only).
5. Set up timing to interface with off-chip memory or peripherals.

Each of these five steps is explained in detail in the following sections. The Port selection, Multiplexed mode selection, and Mode bits are located in the EMI0CF register shown in SFR Definition .

18.3. Port Configuration

The External Memory Interface appears on Ports 1, 2, 3, and 4 when it is used for off-chip memory access. When the EMIF is used, the Crossbar should be configured to skip over the /RD control line (P1.6) and the /WR control line (P1.7) using the P1SKIP register. When the EMIF is used in multiplexed mode, the Crossbar should also skip over the ALE control line (P1.5). For more information about configuring the Crossbar, see Section “20.6. Special Function Registers for Accessing and Configuring Port I/O” on page 191. The EMIF pinout is shown in Table 18.1 on page 149.

The External Memory Interface claims the associated Port pins for memory operations ONLY during the execution of an off-chip MOVX instruction. Once the MOVX instruction has completed, control of the Port pins reverts to the Port latches or to the Crossbar settings for those pins. See Section “20. Port Input/Output” on page 177 for more information about the Crossbar and Port operation and configuration. **The Port latches should be explicitly configured to “park” the External Memory Interface pins in a dormant state, most commonly by setting them to a logic 1**.

During the execution of the MOVX instruction, the External Memory Interface will explicitly disable the drivers on all Port pins that are acting as Inputs (Data[7:0] during a READ operation, for example). The Output mode of the Port pins (whether the pin is configured as Open-Drain or Push-Pull) is unaffected by the External Memory Interface operation, and remains controlled by the PnMDOUT registers. In most cases, the output modes of all EMIF pins should be configured for push-pull mode.

The C8051F500/1/4/5 devices support both the multiplexed and non-multiplexed modes and the C8051F508/9-F510/1 devices support only multiplexed modes. Accessing off-chip memory is not supported by the C8051F502/3/6/7 devices.

SFR Definition 19.3. OSCICRS: Internal Oscillator Coarse Calibration

Bit	7	6	5	4	3	2	1	0
Name		OSCICRS[6:0]						
Type	R	R/W						
Reset	0	Varies	Varies	Varies	Varies	Varies	Varies	Varies

SFR Address = 0xA2; SFR Page = 0x0F;

Bit	Name	Function
7	Unused	Read = 0; Write = Don't Care
6:0	OSCICRS[6:0]	**Internal Oscillator Coarse Calibration Bits.** These bits determine the internal oscillator period. When set to 0000000b, the internal oscillator operates at its slowest setting. When set to 1111111b, the internal oscillator operates at its fastest setting. The reset value is factory calibrated to generate an internal oscillator frequency of 24 MHz.

SFR Definition 19.4. OSCIFIN: Internal Oscillator Fine Calibration

Bit	7	6	5	4	3	2	1	0
			OSCIFIN[5:0]					
Type	R	R	R/W					
Reset	0	0	Varies	Varies	Varies	Varies	Varies	Varies

SFR Address = 0x9E; SFR Page = 0x0F;

Bit	Name	Function
7:6	Unused	Read = 00b; Write = Don't Care
5:0	OSCIFIN[5:0]	**Internal Oscillator Fine Calibration Bits.** These bits are fine adjustment for the internal oscillator period. The reset value is factory calibrated to generate an internal oscillator frequency of 24 MHz.

19.4.1. External Crystal Example

If a crystal or ceramic resonator is used as an external oscillator source for the MCU, the circuit should be configured as shown in Figure 19.1, Option 1. The External Oscillator Frequency Control value (XFCN) should be chosen from the Crystal column of the table in SFR Definition 19.6 (OSCXCN register). For example, an 11.0592 MHz crystal requires an XFCN setting of 111b and a 32.768 kHz Watch Crystal requires an XFCN setting of 001b. After an external 32.768 kHz oscillator is stabilized, the XFCN setting can be switched to 000 to save power. It is recommended to enable the missing clock detector before switching the system clock to any external oscillator source.

When the crystal oscillator is first enabled, the oscillator amplitude detection circuit requires a settling time to achieve proper bias. Introducing a delay of 1 ms between enabling the oscillator and checking the XTLVLD bit will prevent a premature switch to the external oscillator as the system clock. Switching to the external oscillator before the crystal oscillator has stabilized can result in unpredictable behavior. The recommended procedure is:

1. Force XTAL1 and XTAL2 to a high state. This involves enabling the Crossbar and writing 1 to the port pins associated with XTAL1 and XTAL2.
2. Configure XTAL1 and XTAL2 as analog inputs using.
3. Enable the external oscillator.
4. Wait at least 1 ms.
5. Poll for XTLVLD => 1.
6. Enable the Missing Clock Detector.
7. Switch the system clock to the external oscillator.

Important Note on External Crystals: Crystal oscillator circuits are quite sensitive to PCB layout. The crystal should be placed as close as possible to the XTAL pins on the device. The traces should be as short as possible and shielded with ground plane from any other traces which could introduce noise or interference.

The capacitors shown in the external crystal configuration provide the load capacitance required by the crystal for correct oscillation. These capacitors are "in series" as seen by the crystal and "in parallel" with the stray capacitance of the XTAL1 and XTAL2 pins.

Note: The desired load capacitance depends upon the crystal and the manufacturer. Refer to the crystal data sheet when completing these calculations.

For example, a tuning-fork crystal of 32.768 kHz with a recommended load capacitance of 12.5 pF should use the configuration shown in Figure 19.1, Option 1. The total value of the capacitors and the stray capacitance of the XTAL pins should equal 25 pF. With a stray capacitance of 3 pF per pin, the 22 pF capacitors yield an equivalent capacitance of 12.5 pF across the crystal, as shown in Figure 19.3.

Equation 19.2. C Mode Oscillator Frequency

$$f = (KF)/(R \times V_{DD})$$

For example: Assume V_{DD} = 2.1 V and f = 75 kHz:

f = KF / (C x VDD)

0.075 MHz = KF / (C x 2.1)

Since the frequency of roughly 75 kHz is desired, select the K Factor from the table in SFR Definition 19.6 (OSCXCN) as KF = 7.7:

0.075 MHz = 7.7 / (C x 2.1)

C x 2.1 = 7.7 / 0.075 MHz

C = 102.6 / 2.0 pF = 51.3 pF

Therefore, the XFCN value to use in this example is 010b.

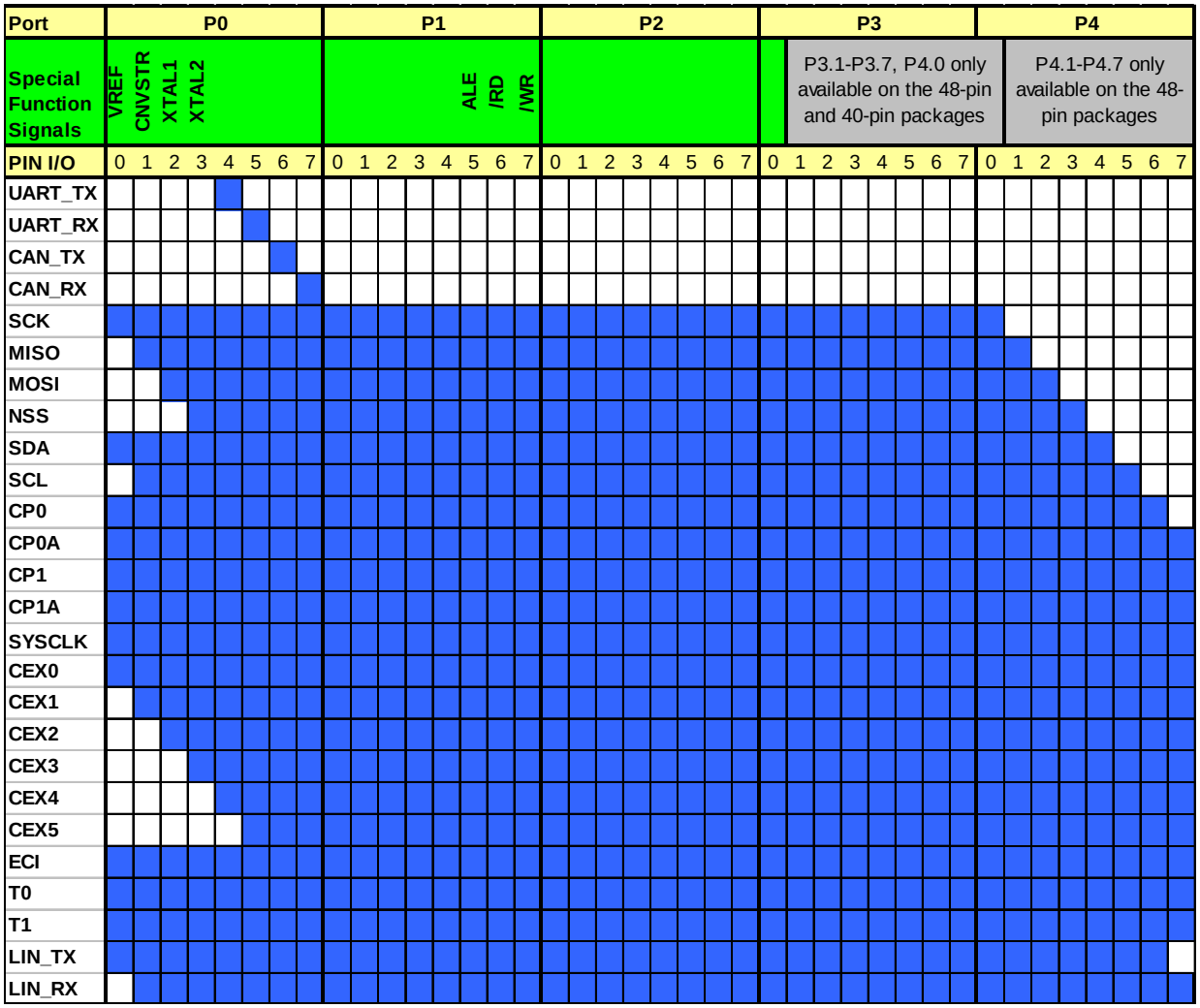

Figure 20.3. Peripheral Availability on Port I/O Pins

Registers XBR0, XBR1, and XBR2 are used to assign the digital I/O resources to the physical I/O Port pins. Note that when the SMBus is selected, the Crossbar assigns both pins associated with the SMBus (SDA and SCL); and similarly when the UART, CAN or LIN are selected, the Crossbar assigns both pins associated with the peripheral (TX and RX). UART0 pin assignments are fixed for bootloading purposes: UART TX0 is always assigned to P0.4; UART RX0 is always assigned to P0.5. CAN0 pin assignments are fixed to P0.6 for CAN_TX and P0.7 for CAN_RX. Standard Port I/Os appear contiguously after the prioritized functions have been assigned.

Important Note: The SPI can be operated in either 3-wire or 4-wire modes, pending the state of the NSSMD1–NSSMD0 bits in register SPI0CN. According to the SPI mode, the NSS signal may or may not be routed to a Port pin.

As an example configuration, if CAN0, SPI0 in 4-wire mode, and PCA0 Modules 0, 1, and 2 are enabled on the crossbar with P0.1, P0.2, and P0.5 skipped, the registers should be set as follows: XBR0 = 0x06 (CAN0 and SPI0 enabled), XBR1 = 0x0C (PCA0 modules 0, 1, and 2 enabled), XBR2 = 0x40 (Crossbar enabled), and P0SKIP = 0x26 (P0.1, P0.2, and P0.5 skipped). The resulting crossbar would look as shown in Figure 20.4.

SFR Definition 21.3. LIN0CF: LIN0 Control Mode Register

Bit	7	6	5	4	3	2	1	0
Name	LINEN	MODE	ABAUD					
Type	R/W	R/W	R/W	R	R	R	R	R
Reset	0	1	1	0	0	0	0	0

SFR Address = 0xC9; SFR Page = 0x0F

Bit	Name	Function
7	LINEN	**LIN Interface Enable Bit.** 0: LIN0 is disabled. 1: LIN0 is enabled.
6	MODE	**LIN Mode Selection Bit.** 0: LIN0 operates in slave mode. 1: LIN0 operates in master mode.
5	ABAUD	**LIN Mode Automatic Baud Rate Selection.** This bit only has an effect when the MODE bit is configured for slave mode. 0: Manual baud rate selection is enabled. 1: Automatic baud rate selection is enabled.
4:0	Unused	Read = 00000b; Write = Don't Care

LIN Register Definition 21.5. LIN0CTRL: LIN0 Control Register

Bit	7	6	5	4	3	2	1	0
Name	STOP	SLEEP	TXRX	DTACK	RSTINT	RSTERR	WUPREQ	STREQ
Type	W	R/W	R/W	R/W	W	W	R/W	R/W
Reset	0	0	0	0	0	0	0	0

Indirect Address = 0x08

Bit	Name	Function
7	STOP	**Stop Communication Processing Bit. (slave mode only)** This bit always reads as 0. 0: No effect. 1: Block the processing of LIN communications until the next SYNC BREAK signal.
6	SLEEP	**Sleep Mode Bit. (slave mode only)** 0: Wake the device after receiving a Wakeup interrupt. 1: Put the device into sleep mode after receiving a Sleep Mode frame or a bus idle timeout.
5	TXRX	**Transmit / Receive Selection Bit.** 0: Current frame is a receive operation. 1: Current frame is a transmit operation.
4	DTACK	**Data Acknowledge Bit. (slave mode only)** Set to 1 after handling a data request interrupt to acknowledge the transfer. The bit will automatically be cleared to 0 by the LIN controller.
3	RSTINT	**Reset Interrupt Bit.** This bit always reads as 0. 0: No effect. 1: Reset the LININT bit (LIN0ST.3).
2	RSTERR	**Reset Error Bit.** This bit always reads as 0. 0: No effect. 1: Reset the error bits in LIN0ST and LIN0ERR.
1	WUPREQ	**Wakeup Request Bit.** Set to 1 to terminate sleep mode by sending a wakeup signal. The bit will automatically be cleared to 0 by the LIN controller.
0	STREQ	**Start Request Bit. (master mode only)** 1: Start a LIN transmission. This should be set only after loading the identifier, data length and data buffer if necessary. The bit is reset to 0 upon transmission completion or error detection.

LIN Register Definition 21.11. LIN0ID: LIN0 Identifier Register

Bit	7	6	5	4	3	2	1	0
Name			ID[5:0]					
Type	R	R	R/W					
Reset	0	0	0	0	0	0	0	0

Indirect Address = 0x0E

Bit	Name	Function
7:6	Unused	Read = 00b; Write = Don't Care.
5:0	ID[5:0]	**LIN Identifier Bits.** These bits form the data identifier. If the LINSIZE bits (LIN0SIZE[3:0]) are 1111b, bits ID[5:4] are used to determine the data size and are interpreted as follows: 00: 2 bytes 01: 2 bytes 10: 4 bytes 11: 8 bytes

23.1. Supporting Documents

It is assumed the reader is familiar with or has access to the following supporting documents:

1. The I^2C-Bus and How to Use It (including specifications), Philips Semiconductor.
2. The I^2C-Bus Specification—Version 2.0, Philips Semiconductor.
3. System Management Bus Specification—Version 1.1, SBS Implementers Forum.

23.2. SMBus Configuration

Figure 23.2 shows a typical SMBus configuration. The SMBus specification allows any recessive voltage between 3.0 V and 5.0 V; different devices on the bus may operate at different voltage levels. The bi-directional SCL (serial clock) and SDA (serial data) lines must be connected to a positive power supply voltage through a pullup resistor or similar circuit. Every device connected to the bus must have an open-drain or open-collector output for both the SCL and SDA lines, so that both are pulled high (recessive state) when the bus is free. The maximum number of devices on the bus is limited only by the requirement that the rise and fall times on the bus not exceed 300 ns and 1000 ns, respectively.

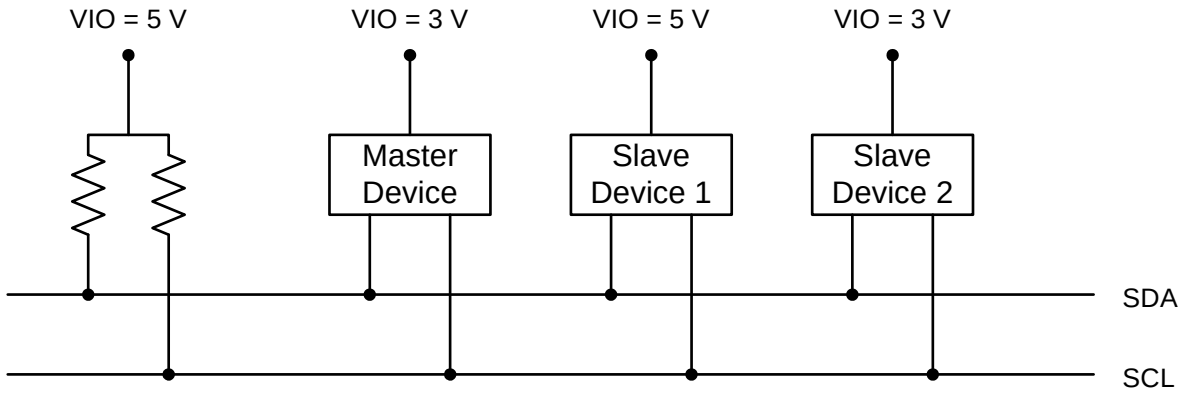

Figure 23.2. Typical SMBus Configuration

23.3. SMBus Operation

Two types of data transfers are possible: data transfers from a master transmitter to an addressed slave receiver (WRITE), and data transfers from an addressed slave transmitter to a master receiver (READ). The master device initiates both types of data transfers and provides the serial clock pulses on SCL. The SMBus interface may operate as a master or a slave, and multiple master devices on the same bus are supported. If two or more masters attempt to initiate a data transfer simultaneously, an arbitration scheme is employed with a single master always winning the arbitration. It is not necessary to specify one device as the Master in a system; any device who transmits a START and a slave address becomes the master for the duration of that transfer.

A typical SMBus transaction consists of a START condition followed by an address byte (Bits7–1: 7-bit slave address; Bit0: R/W direction bit), one or more bytes of data, and a STOP condition. Bytes that are received (by a master or slave) are acknowledged (ACK) with a low SDA during a high SCL (see Figure 23.3). If the receiving device does not ACK, the transmitting device will read a NACK (not acknowledge), which is a high SDA during a high SCL.

The direction bit (R/W) occupies the least-significant bit position of the address byte. The direction bit is set to logic 1 to indicate a "READ" operation and cleared to logic 0 to indicate a "WRITE" operation.

26.1. Timer 0 and Timer 1

Each timer is implemented as a 16-bit register accessed as two separate bytes: a low byte (TL0 or TL1) and a high byte (TH0 or TH1). The Counter/Timer Control register (TCON) is used to enable Timer 0 and Timer 1 as well as indicate status. Timer 0 interrupts can be enabled by setting the ET0 bit in the IE register (Section “14.2. Interrupt Register Descriptions” on page 120); Timer 1 interrupts can be enabled by setting the ET1 bit in the IE register (Section “14.2. Interrupt Register Descriptions” on page 120). Both counter/timers operate in one of four primary modes selected by setting the Mode Select bits T1M1–T0M0 in the Counter/Timer Mode register (TMOD). Each timer can be configured independently. Each operating mode is described below.

26.1.1. Mode 0: 13-bit Counter/Timer

Timer 0 and Timer 1 operate as 13-bit counter/timers in Mode 0. The following describes the configuration and operation of Timer 0. However, both timers operate identically, and Timer 1 is configured in the same manner as described for Timer 0.

The TH0 register holds the eight MSBs of the 13-bit counter/timer. TL0 holds the five LSBs in bit positions TL0.4–TL0.0. The three upper bits of TL0 (TL0.7–TL0.5) are indeterminate and should be masked out or ignored when reading. As the 13-bit timer register increments and overflows from 0x1FFF (all ones) to 0x0000, the timer overflow flag TF0 (TCON.5) is set and an interrupt will occur if Timer 0 interrupts are enabled.

The C/T0 bit (TMOD.2) selects the counter/timer's clock source. When C/T0 is set to logic 1, high-to-low transitions at the selected Timer 0 input pin (T0) increment the timer register (Refer to Section “20.3. Priority Crossbar Decoder” on page 180 for information on selecting and configuring external I/O pins). Clearing C/T selects the clock defined by the T0M bit (CKCON.3). When T0M is set, Timer 0 is clocked by the system clock. When T0M is cleared, Timer 0 is clocked by the source selected by the Clock Scale bits in CKCON (see SFR Definition 26.1).

Setting the TR0 bit (TCON.4) enables the timer when either GATE0 (TMOD.3) is logic 0 or the input signal $\overline{INT0}$ is active as defined by bit IN0PL in register IT01CF (see SFR Definition 14.7). Setting GATE0 to 1 allows the timer to be controlled by the external input signal $\overline{INT0}$ (see Section “14.2. Interrupt Register Descriptions” on page 120), facilitating pulse width measurements.

TR0	GATE0	$\overline{INT0}$	Counter/Timer
0	X	X	Disabled
1	0	X	Enabled
1	1	0	Disabled
1	1	1	Enabled
Note: X = Don't Care			

Setting TR0 does not force the timer to reset. The timer registers should be loaded with the desired initial value before the timer is enabled.

TL1 and TH1 form the 13-bit register for Timer 1 in the same manner as described above for TL0 and TH0. Timer 1 is configured and controlled using the relevant TCON and TMOD bits just as with Timer 0. The input signal $\overline{INT1}$ is used with Timer 1; the $\overline{INT1}$ polarity is defined by bit IN1PL in register IT01CF (see SFR Definition 14.7).

27. Programmable Counter Array

The Programmable Counter Array (PCA0) provides enhanced timer functionality while requiring less CPU intervention than the standard 8051 counter/timers. The PCA consists of a dedicated 16-bit counter/timer and six 16-bit capture/compare modules. Each capture/compare module has its own associated I/O line (CEXn) which is routed through the Crossbar to Port I/O when enabled. The counter/timer is driven by a programmable timebase that can select between six sources: system clock, system clock divided by four, system clock divided by twelve, the external oscillator clock source divided by 8, Timer 0 overflows, or an external clock signal on the ECI input pin. Each capture/compare module may be configured to operate independently in one of six modes: Edge-Triggered Capture, Software Timer, High-Speed Output, Frequency Output, 8 to 11-Bit PWM, or 16-Bit PWM (each mode is described in Section "27.3. Capture/Compare Modules" on page 289). The external oscillator clock option is ideal for real-time clock (RTC) functionality, allowing the PCA to be clocked by a precision external oscillator while the internal oscillator drives the system clock. The PCA is configured and controlled through the system controller's Special Function Registers. The PCA block diagram is shown in Figure 27.1

Important Note: The PCA Module 5 may be used as a watchdog timer (WDT), and is enabled in this mode following a system reset. **Access to certain PCA registers is restricted while WDT mode is enabled**. See Section 27.4 for details.

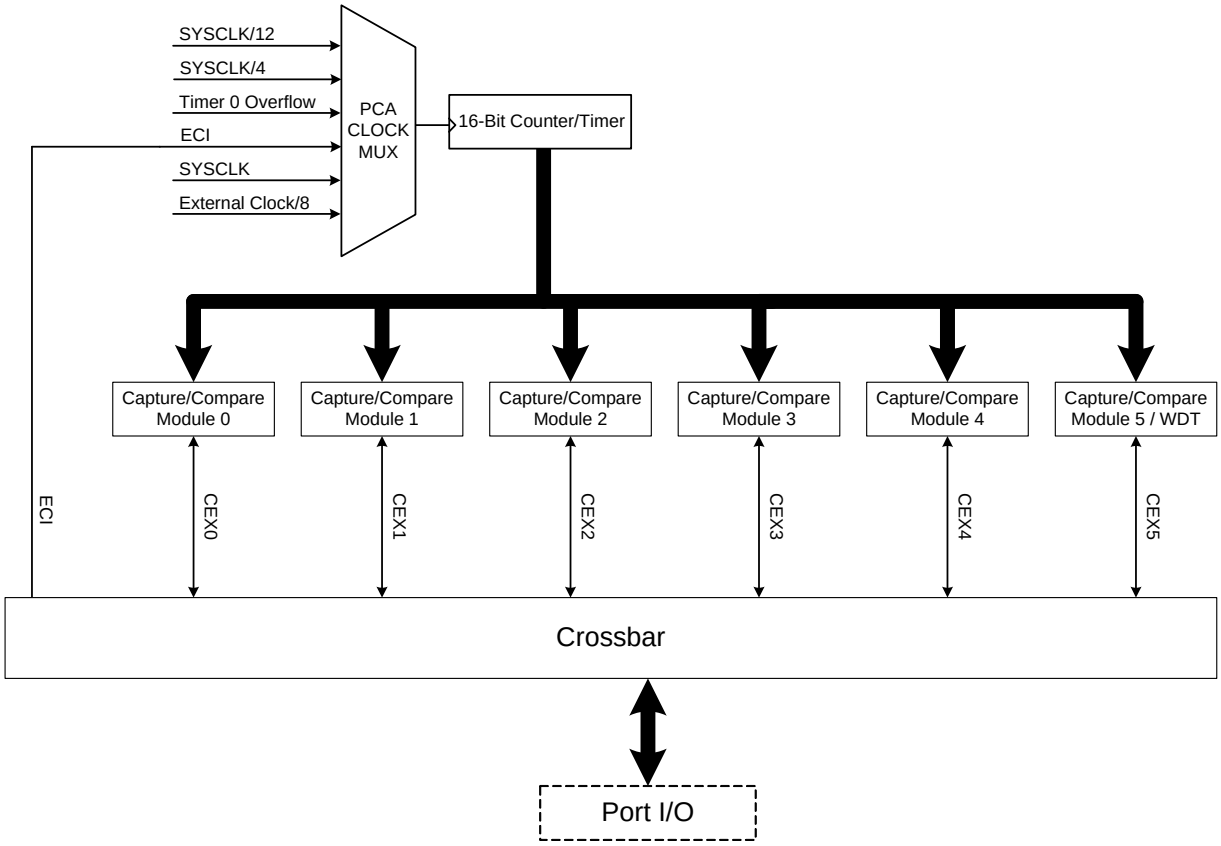

Figure 27.1. PCA Block Diagram

27.5. Register Descriptions for PCA0

Following are detailed descriptions of the special function registers related to the operation of the PCA.

SFR Definition 27.1. PCA0CN: PCA Control

Bit	7	6	5	4	3	2	1	0
Name	CF	CR	CCF5	CCF4	CCF3	CCF2	CCF1	CCF0
Type	R/W	R/W	R/W	R/W	R/W	R/W	R/W	R/W
Reset	0	0	0	0	0	0	0	0

SFR Address = 0xD8; Bit-Addressable; SFR Page = 0x00

Bit	Name	Function
7	CF	**PCA Counter/Timer Overflow Flag.** Set by hardware when the PCA Counter/Timer overflows from 0xFFFF to 0x0000. When the Counter/Timer Overflow (CF) interrupt is enabled, setting this bit causes the CPU to vector to the PCA interrupt service routine. This bit is not automatically cleared by hardware and must be cleared by software.
6	CR	**PCA Counter/Timer Run Control.** This bit enables/disables the PCA Counter/Timer. 0: PCA Counter/Timer disabled. 1: PCA Counter/Timer enabled.
5	CCF5	**PCA Module 5 Capture/Compare Flag.** This bit is set by hardware when a match or capture occurs. When the CCF5 interrupt is enabled, setting this bit causes the CPU to vector to the PCA interrupt service routine. This bit is not automatically cleared by hardware and must be cleared by software.
4	CCF4	**PCA Module 4 Capture/Compare Flag.** This bit is set by hardware when a match or capture occurs. When the CCF4 interrupt is enabled, setting this bit causes the CPU to vector to the PCA interrupt service routine. This bit is not automatically cleared by hardware and must be cleared by software.
3	CCF3	**PCA Module 3 Capture/Compare Flag.** This bit is set by hardware when a match or capture occurs. When the CCF3 interrupt is enabled, setting this bit causes the CPU to vector to the PCA interrupt service routine. This bit is not automatically cleared by hardware and must be cleared by software.
2	CCF2	**PCA Module 2 Capture/Compare Flag.** This bit is set by hardware when a match or capture occurs. When the CCF2 interrupt is enabled, setting this bit causes the CPU to vector to the PCA interrupt service routine. This bit is not automatically cleared by hardware and must be cleared by software.
1	CCF1	**PCA Module 1 Capture/Compare Flag.** This bit is set by hardware when a match or capture occurs. When the CCF1 interrupt is enabled, setting this bit causes the CPU to vector to the PCA interrupt service routine. This bit is not automatically cleared by hardware and must be cleared by software.
0	CCF0	**PCA Module 0 Capture/Compare Flag.** This bit is set by hardware when a match or capture occurs. When the CCF0 interrupt is enabled, setting this bit causes the CPU to vector to the PCA interrupt service routine. This bit is not automatically cleared by hardware and must be cleared by software.